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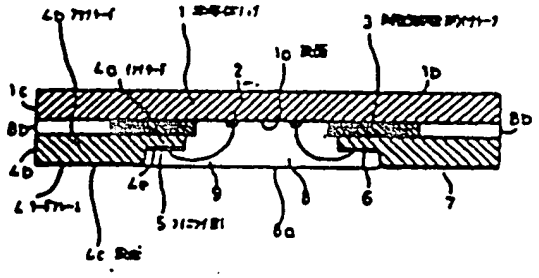
(54)【発明の名称】半導体装置

(57)【要約】
【課題】半導体チップの上に同一サイズのリードフレームを配せるCSP（ChipScale Package）構造において，パッケージ厚さをより薄くする。
【解決手段】半導体チップ1に貼り付けるリードフレーム4は，半導体チップ1と略同一サイズとする。リードフレーム4のインナリード4aの狭部4eにコイニングを施して厚みを薄らしたコイニング部5を形成する。両面接着剤付テープ3を介してリードフレーム4と半導体チップ1とを狭部4d，1cを合わせて貼り付ける。インナリード4aのコイニング部5と半導体チップ1のボンディングパッドとをボンディングワイヤ9で接続する。半導体チップ1の広部1aにモールド樹脂8を封止し，封止樹脂広部8aにアウタリード4bの広部4cのみを突出させる。



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【特許請求の範囲】

【請求項1】半導体チップの表面に半導体チップと略同一サイズのリードフレームを重ね合わせて接着剤を介して貼り付け，リードフレームのインナリードと半導体チップとをボンディングワイヤで接続し，アウタリードの表面と面一となるように半導体チップの表面側をモールド樹脂で封止して，封止樹脂表面にアウタリードの表面を露出させた半導体装置において，インナリードに接続されるボンディングワイヤがアウタリードの表面を超えないように，インナリードの表面側の厚みを減らしてインナリード表面をアウタリード表面より一段低くしたことを特徴とする半導体装置。

【請求項2】上記リードフレームのサイズを半導体チップよりやや大きめに形成し，該リードフレームを半導体チップの表面に重ね合わせたとき形成される端面間のギャップもモールド樹脂で封止するようにした請求項1に記載の半導体装置。

【請求項3】上記半導体チップの表面にリードフレームを貼り付ける接着剤を，インナリード側のみならずアウタリード側にも介在させた請求項1または2に記載の半導体装置。

【発明の詳細な説明】

【0001】

【発明の属する技術分野】本発明はリードフレームを使用した半導体装置に係り，特にチップサイズと略同一のサイズをもつ薄型かつ小型の半導体パッケージ構造に関するものである。

【0002】

【従来の技術】大容量のDRAM（Dynamic Random Access Memory）では，高密度実装の要求に対応して，比較的小さなパッケージに大形化した半導体チップを収納できるLOC（Lead On Chip）構造が採用されているが，容量の増加により更にチップサイズレベルにまで小形化されたパッケージが要求されるようになってきた。また，電子機器用の半導体パッケージも，パソコン，ファックス，パーソナル電話機，ICカード等のサイズの縮小に伴って，より小形化することが要求されている。しかも，この小形化は，単にパッケージの専有する面積にのみ求められるのではなく，パッケージの厚さ方向にも求められている。

【0003】従来，これらの要請に応えるものとして，リードの一部のみをパッケージの底面に露出させたCSP（Chip Scale Package）と呼ばれる半導体装置が提案されている（特開平6－132453号公報）。具体的には，図7に示すように，半導体チップ21の配線面（表面）21aに半導体チップ21と同一サイズのリードフレーム22を位置を合わせて接着剤23で貼り付ける。リードフレーム22のインナリード22eと半導体チップ21とをボンディングワイヤ24で接続した後，モールド樹脂25で封止する時，半導体チップ21の表面側をモールド樹脂25で封止して，モールド樹脂25の表面25aにアウタリード22bの表面22cを露出させたものである。

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【0004】ここに，インナリード22eと半導体チップ21とを接続するボンディングワイヤ24が，アウタリード22bの表面22cと面一にしたモールド樹脂25の表面25aからはみだたないように，リードに段差を設ける必要があるが，この従来例では，リードフレーム22をダウンセット加工することによって，インナリード22aをアウタリード22bよりも一段低くしている。

【0005】

【発明が解決しようとする課題】上述した従来技術によって，パッケージの小形化は，パッケージの専有する面積に反映されるばかりでなく，パッケージの厚さ方向にも反映されるようになってきた。しかし，リードフレームをダウンセット加工することによってリードに段差を設けるようにしているので，リード厚を超えた加工深さが必要となり，その分，パッケージ厚さを薄くできない。

【0006】また，パッケージのサイズが半導体チップ1と同一であると，最小のパッケージを得ることができるが，半導体チップ1の大きさのばらつきによっては，モールド樹脂封止時にモールド金型が半導体チップ1の一部を破損してしまうおそれがある。

【0007】さらに，半導体チップへのリードフレームの接着固定は，インナリード側のみで行なっているため，モールド樹脂封止の際に，アウタリード側の厚み方向での固定が十分でない場合が生じるが，固定が十分でないと，アウタリードの表面にモールド樹脂が薄く回り込み，表面を削り出す必要があった。

【0008】本発明の目的は，上述した従来技術の問題点を解消して，パッケージ厚さをより薄くできる半導体装置を提供することにある。また，本発明の目的は，モールド樹脂封止時，半導体チップが破損しない半導体装置を提供することにある。さらに，本発明の目的は，モールド樹脂封止後，アウタリード表面の削り出しを必要としない半導体装置を提供することにある。

【0009】

【課題を解決するための手段】本発明の半導体装置は，半導体チップの表面に半導体チップと略同一サイズのリードフレームを重ね合わせて接着剤を介して貼り付け，リードフレームのインナリードと半導体チップとをボンディングワイヤで接続し，アウタリードの表面と面一となるように半導体チップの表面側をモールド樹脂で封止して，封止樹脂表面にアウタリードの表面を露出させた半導体装置において，インナリードに接続されるボンディングワイヤがアウタリードの表面を超えないように，インナリードの表面側の厚みを減らしてインナリード表面をアウタリード表面より一段低くしたものである。こ

のようにインナリードの厚みをアウタリードよりし減らしてインナリードをアウタリードより一段低くできるようにすると、リードをダウンセットする場合にに比して、パッケージ厚さをより薄くすることができる。

【0010】また、このような本発明の半導体装置において、リードフレームのサイズを半導体チップよりやや大きめに形成し、リードフレームを半導体チップの底面に重ねあわせたときに形成される底面間のギャップもモールド樹脂で封止することが、半導体チップの底面を有効に保護できる。また、半導体チップの底面にリードフレームを貼り付ける際前記、インナリード側のみならずアウタリード側にし介在させることが、アウタリードの底面へのモールド樹脂の回り込みを防止できる。

【0011】

【発明の実施の形態】以下に本発明の半導体装置の実施の形態を図面を用いて詳細に説明する。図1は、半導体チップ1上に同一サイズのリードフレーム4を載せたCSP構造の断面図である。

【0012】半導体チップ1は、その配線面である表面1aの中央近傍にボンディングパッド2が配置されて構成される。この半導体チップ1の底面1aに貼り付けられるリードフレーム4は、半導体チップ1と同一サイズで形成され、半導体チップ1と接続するためのインナリード4aと、外部端子となるアウタリード4bとを有する。半導体チップ1とリードフレーム4との貼付けは、半導体チップ1の底面1cとリードフレーム4の底面4dとが一致するように、半導体チップ1とリードフレーム4とを重ねあわせて、両面接着剤付テープ3を介して行う。

【0013】リードフレーム4は折曲していない代りに、一部の厚さを減らして薄くしてある。すなわち、リードフレーム4のインナリード4aは、その貼付け部と反対側（底面4e）側をコイニングしてアウタリード4bよりし薄くしたコイニング部5を形成し、インナリード4aと半導体チップ1のボンディングパッド2とを接続するボンディングワイヤ9の高さをアウタリード4bの貼付け部と反対側（底面4e）よりし低くなるようにしてある。

【0014】このようにして厚さを減らしてアウタリード4bの底面4eよりし一段低くしたインナリード4aのコイニング部5には凹のっぺ6が形成され、凹のっぺ6が形成されたコイニング部5と半導体チップ1の中央近傍に配置されたボンディングパッド2とがボンディングワイヤ9によって接続される。コイニング部5が一段低くなっているため、ボンディングワイヤ9の高さは、アウタリード4bの底面4eより低く収めることができる。

【0015】モールド樹脂8による封止は、半導体チップ1の底面1aにて行なわれる。モールド樹脂8の底面をアウタリード4bの底面4eと同一面をにして、インナリード4aおよびボンディングワイヤ9などをモールド樹脂8中に埋めて保護するが、アウタリード4bの底面4eに封止樹脂底面8aに露出できる。このことパッケージの厚みを小さく、かつパッケージの底さを浅くするために、モールド樹脂8は、リードフレームの底面4d及び半導体チップ1の底面1c及び半導体チップ1の底面1bに回りこまないようにする。

【0016】このように形成された半導体パッケージは、コイニングによってリードに段差を設けているため、従来のようにリードフレームをダウンセットする必要はない。また、パッケージ厚さは半導体チップ厚、底面接着剤付テープ厚、及び1段のリード厚を合計した厚さとなり、ダウンセットが必要するリード部の2段以上の加工段差がリード部分に必要されないため、パッケージの厚さをより薄くすることができる。

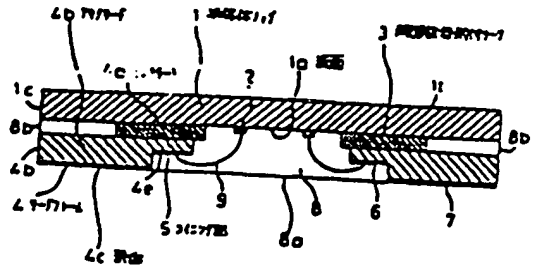
【0017】上記した半導体パッケージを製造するには、まず、モールド樹脂8の底面8bを半導体チップ1の底面1cに一致させるために、パッケージに使用されるリードフレーム4は、その樹脂ダムバー17の位置を、図2に示すように、一点鎖線で示した半導体チップ1の外周に沿って配置するように構成する。また、パッケージ製造時に使用するモールド金型は、半導体チップ1の外形とほぼ同じ大きさとし、半導体チップ1の底面1b側にモールド樹脂8が回らないようにして、半導体チップの底面側のみをモールドする。なお、リードフレーム4の底面4dは樹脂ダムバー17の切断面となる。

【0018】モールド後、樹脂ダムバー17を金型で切断し、リード4a、4bを個々に切り離す。ここで、樹脂ダムバー17を切断する際に、モールド樹脂8の底面8aに位置するアウタリード4bの底面4eに、半田との濡れが良好な凹のっぺ7をインナリード4aのコイニング部5の凹のっぺ6と同時に打っておくのがよい。こうするとアウタリード4bの底面の外装半田のっぺは不要となり、コスト低減できるとともに、モールド後、パッケージにダメージを与える工程を減らすことができる点でも有利である。

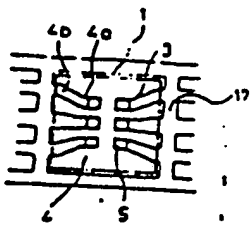
【0019】本製造方法によれば、従来より行われているLOCリードフレームの製造工程、および樹脂モールド工程をそのまま、または、一部変更して利用することができるため、従来のモールドパッケージと比較して価格的に同等でありながら、より小型かつ薄型のパッケージを得ることができる。

【0020】ところで、図1に示すパッケージ製造のモールド工程では、パッケージのサイズが半導体チップ1と同一であるため、半導体チップ1の大きさのばらつきによっては、モールド金型が半導体チップ1の一部を破損してしまうことが予想される。このような場合には、図3に示すように　半導体チップ1に対してモールド樹脂を若干広大する設定を行うことよって解決できる。すなわち、リードフレーム4のサイズを半導体チップ1よりやや大きめに形成し、このやや大きめに形成したリード

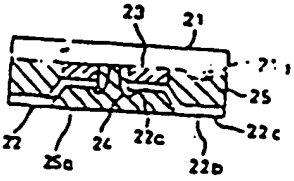
【図1】



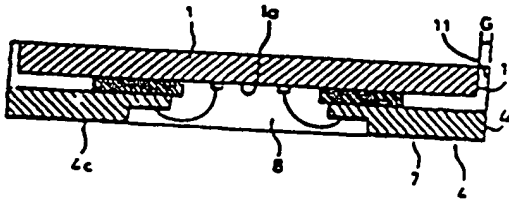
【図2】



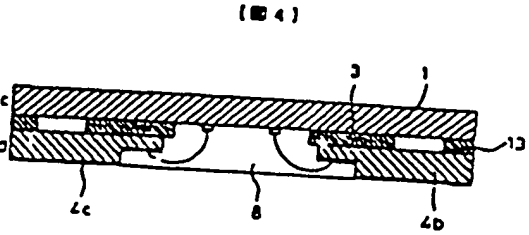
【図7】



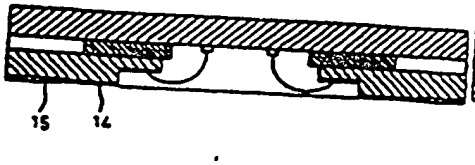
【図3】



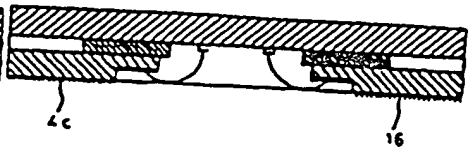
【図4】



【図5】



【図6】



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Japanese Patent Laid-Open Publication No. Heisei 9-92775

[TITLE OF THE INVENTION]

Semiconductor Device

[CLAIMS]

1. A semiconductor device including a semiconductor chip, a lead frame having a size substantially equal to that of the semiconductor chip, the lead frame being bonded to a surface of the semiconductor chip by an adhesive layer interposed therebetween under the condition in which the lead frame is overlapped with the semiconductor chip, bonding wires adapted to bond inner leads included in the lead frame to the semiconductor chip, and a resin encapsulate adapted to encapsulate a region toward the surface of the semiconductor chip in such a fashion that it has a surface flush with a surface of each of outer leads included in the lead frame to expose the surface of the outer lead at the surface of the resin encapsulate, wherein each of the inner leads has a reduced thickness at a surface thereof in such a fashion that the bonding wire connected to the inner lead does not extend beyond the surface of an associated one of the outer leads, whereby the surface of the inner lead is lower than the surface of the outer lead by one step.

2. The semiconductor device in accordance with claim 1, wherein the size of the lead frame is slightly larger than that of the semiconductor chip, and the resin encapsulate fills a gap defined between corresponding end surfaces of the semiconductor chip and the lead frame when the lead frame is laid on the surface of the semiconductor chip in an overlapped state.

3. The semiconductor device in accordance with claim 1 or 2, wherein the adhesive layer is disposed not only at a region where the inner leads are arranged, but also at a region where the outer leads are arranged.

[DETAILED DESCRIPTION OF THE INVENTION]

[FIELD OF THE INVENTION]

The present invention relates to a semiconductor device using a lead frame, and more particularly to a semiconductor package having a thin and compact structure substantially equal in size to a semiconductor chip packaged therein.

[DESCRIPTION OF THE PRIOR ART]

In DRAMs (Dynamic Random Access Memories) having a large capacity, an LOC (Lead On Chip) structure is mainly

used which is capable of allowing a semiconductor chip having a large size to be packaged in a relatively small package, in order to meet a requirement of high-density mounting. However, the recent demand of an increased capacity has resulted in a requirement of compact semiconductor packages having a size reduced to a chip size level. Similarly, semiconductor packages for electronic appliances such as facsimile machines, personal computers, IC cards, and the like has been required to have a more compact structure in pace with the recent trend of those electronic appliances toward a compactness. Furthermore, such a compactness of a semiconductor package have been required with regard to not only the area occupied by the semiconductor package, but also the thickness of the semiconductor package.

In order to meet such requirements, a semiconductor device has been proposed which is called a "CSP (Chip Scale Package)" (Japanese Patent Laid-open Publication No. Heisei 6-132453). In such a CSP package, each lead is partially exposed at the lower surface of the package. Referring to Fig. 7 illustrating a detailed structure of this CSP package, a lead frame 22 having the same size as that of a semiconductor chip 21 is bonded to the wiring surface of the semiconductor chip 21, that is, the surface 21a, in such a fashion that their corresponding edges are aligned

with each other, by means of an adhesive 23. Inner leads 22a of the lead frame 22 are connected to the semiconductor chip 21 by means of bonding wires 24. In this state, an encapsulating process is carried out using a molding resin 25. In this encapsulating process, the semiconductor chip 21 is encapsulated by the molding resin 25 at its portion toward its surface 21a, thereby causing the surface 22c of each outer lead 22b to be exposed at the surface 25a of the molding resin 25.

In this case, it is necessary to provide a stepped lead structure in order to prevent the bonding wires 24 serving to connect the inner leads 22a to the semiconductor chip 21 from being protruded from the surface 25a of the resin 25 flush with the surfaces 22c of the outer leads 22b. To this end, in this conventional example, the lead frame 22 is subjected to a down-setting process so that each inner lead 22a is lower than an associated one of the outer leads 22c by one step.

[SUBJECT MATTERS TO BE SOLVED BY THE INVENTION]

In accordance with the above mentioned conventional technique, compactness of a semiconductor package can be achieved with regard to not only the area occupied by the semiconductor package, but also the thickness of the semiconductor package. However, since this technique

provides a stepped lead structure by down-setting the lead frame, it requires a machining depth exceeding the lead thickness. For this reason, it is impossible to produce a package having a thickness less than the machining depth.

Where the semiconductor chip 1 has the same size as that of a package to be produced, the package may have a minimized size. However, if the semiconductor chip 1 has a non-uniform size, it may be damaged by a mold during an encapsulating process using the molding resin.

Furthermore, the lead frame may be in a state insufficiently fixed in a thickness direction at its portion near the outer leads during the encapsulating process because the bonding and fixing of the lead frame to the semiconductor chip is achieved at a portion of the lead frame near the inner leads. As a result, the molding resin may spread in the form of a thin film on the outer lead surface. In this case, it is necessary to shave off the resin film coated on the outer lead surface.

An object of the invention is to solve the above mentioned problems involved in the prior art, and to provide a semiconductor device having a reduced package thickness. Another object of the invention is to provide a semiconductor device having a structure capable of preventing its semiconductor chip from being damaged during an encapsulating process using a molding resin. Another

object of the invention is to provide a semiconductor device having a structure capable of eliminating a requirement for its outer lead surface to be shaved off after an encapsulating process.

[MEANS FOR SOLVING THE SUBJECT MATTERS]

The present invention provides a semiconductor device including a semiconductor chip, a lead frame having a size substantially equal to that of the semiconductor chip, the lead frame being bonded to a surface of the semiconductor chip by an adhesive layer interposed therebetween under the condition in which the lead frame is overlapped with the semiconductor chip, bonding wires adapted to bond inner leads included in the lead frame to the semiconductor chip, and a resin encapsulate adapted to encapsulate a region toward the surface of the semiconductor chip in such a fashion that it has a surface flush with a surface of each of outer leads included in the lead frame to expose the surface of the outer lead at the surface of the resin encapsulate, wherein each of the inner leads has a reduced thickness at a surface thereof in such a fashion that the bonding wire connected to the inner lead does not extend beyond the surface of an associated one of the outer leads, whereby the surface of the inner lead is lower than the surface of the outer lead by one step.

In the semiconductor device of the present invention, the size of the lead frame may be slightly larger than that of the semiconductor chip. In this case, the resin encapsulate fills a gap defined between corresponding end surfaces of the semiconductor chip and the lead frame when the lead frame is laid on the surface of the semiconductor chip in an overlapped state. Accordingly, it is possible to effectively prevent the semiconductor chip from being damaged. The adhesive layer may be disposed not only at a region where the inner leads are arranged, but also at a region where the outer leads are arranged. In this case, it is possible to prevent the molding resin from spreading on the outer lead surface.

[PREFERRED EMBODIMENTS OF THE INVENTION]

Hereinafter, preferred embodiments of the present invention will be described in detail in conjunction with the annexed drawings. Fig. 1 is a cross-sectional view illustrating a CSP structure in which a lead frame 4 having the same size of a semiconductor chip 1 is bonded to the semiconductor chip 1.

The semiconductor chip 1 is provided at its wiring surface, namely, a surface 1a, with bonding pads 2. These bonding pads 2 are arranged in the vicinity of the central portion of the surface 1a. The lead frame 4, which is

attached to the surface 1a of the semiconductor chip 1, has the same size as that of the semiconductor chip 1. The lead frame 4 includes inner leads 4a adapted to come into contact with the semiconductor chip 1, and outer leads 4b each serving as an external terminal. The attachment between the semiconductor chip 1 and lead frame 4 is achieved by overlapping the semiconductor chip 1 and lead frame 4 with each other in such a fashion that each end surface 1c of the semiconductor chip 1 is aligned with an associated one of end surfaces 4d of the lead frame 4, and interposing a double-sided adhesive tape 3 between the overlapped semiconductor chip 1 and lead frame 4.

The lead frame 4 has a structure not bent, but having a reduced thickness at a desired portion thereof. That is, each inner lead 4a has a coining portion 5 having a thickness less than that of an associated one of the outer leads 4b. The coining portion 5 is formed by coining a surface of the inner lead 4a opposite to the bonding surface of the inner lead 4a, that is, a surface 4c. Accordingly, bonding wires 9, which connect the inner leads 4a to bonding pads 2 of the semiconductor chip 1 respectively, have a height lower than a surface of each outer lead 4b opposite to the bonding surface of the outer lead 4b, that is, the surface 4c.

For the coining portion 5 of each inner lead 4a

arranged at a level lower than the surface 4c of the associated outer lead 4b by virtue of the above mentioned thickness reduction, a silver plating process is conducted to form a silver plating film 6. The coining portions 5 formed with the silver plating films 6 are connected with the bonding pads 2 arranged near the central portion of the semiconductor chip 1 by means of the bonding wires 9, respectively. Since each coining portion 5 is arranged at a level lower than the surface 4c of the associated outer lead 4b by one step, the associated bonding wire 9 can be controlled to have a height lower than the surface 4c of the outer lead 4b.

An encapsulating process using a molding resin is conducted at a region toward the surface 1a of the semiconductor chip 1, thereby forming a resin encapsulate 8. The thickness of the resin encapsulate 8 is determined in such a fashion that the resin encapsulate 8 is flush with the surfaces 4c of the outer leads 4b at its surface 8a. The inner leads 4a and bonding wires 9 are encapsulated by the resin encapsulate 8 so that they are protected. The surfaces 4c of the outer leads 4b are exposed at the surface 8a of the resin encapsulate 8. In order to reduce the area of the package while reducing the thickness of the package, the resin encapsulate 8 is prevented from extending beyond each end surface 4d of the

lead frame 4, each end surface 1c of the semiconductor chip 1c, and the surface 1b of the semiconductor chip 1.

Since the semiconductor package configured as mentioned above has a stepped lead structure formed using a coining process, it is unnecessary for its lead frame to be down-set. The semiconductor package has a thickness corresponding to the sum of the thickness of the semiconductor chip, the thickness of the double-sided adhesive tape, and the thickness of one lead sheet. The thickness of the semiconductor package can be minimized because the lead portion of the semiconductor package involves no machining depth, corresponding to at least two times the lead thickness, required in a down-set structure.

In the fabrication of the above mentioned semiconductor package, the lead frame 4 used to fabricate the semiconductor package is arranged with respect to the semiconductor chip 1 in such a fashion that its resin dam bars 17 extend along the peripheral edges of the semiconductor chip 1 indicated by dotted lines in Fig. 2, so as to align each end surface 8b of the resin encapsulate 8 with the associated end surface 1c of the semiconductor chip 1. The mold used in the fabrication of the semiconductor package has a size substantially equal to the size of the semiconductor chip 1. The resin encapsulate 8 is molded only at a region toward the surface 1a of the

semiconductor chip 1 while being prevented from spreading on the surface 1b of the semiconductor chip 1. Each resin dam bar 17 is cut along the associated end surface 4d of the lead frame 4.

After molding, the resin dam bars 17 are cut from the mold, thereby achieving a separation of the leads 4a and 4b. It is desirable that, prior to the cutting of the resin dam bars 17, a silver plating film 7 providing a good flowability of solder is formed on the surfaces 4c of the outer leads 4b exposed at the surface 8a of the resin encapsulate 8. The formation of the silver plating film 7 may be conducted simultaneously with the formation of the silver plating film 6 on the coining portions 5 of the inner leads 4a. In this case, it is unnecessary to conduct an external solder plating process for the surfaces of the outer leads 4b. Accordingly, it is possible to reduce the costs. Also, there is an advantage in that the number of processes, which may damage the package after the completion of the molding process, is reduced.

In accordance with the fabrication method according to the present invention, it is possible to use the fabrication process for LOC lead frames and the resin molding process associated therewith as they are or while partially eliminating them. Therefore, it is possible to obtain a package having a more compact and thinner

structure while being equivalent in costs, as compared to conventional molded packages.

In the semiconductor package structure shown in Fig. 1, however, if the semiconductor chip 1 has a deviation in size, the mold may then damage a part of the semiconductor chip 1. This is because the package has the same size as the semiconductor chip 1 at its molding region. Such a problem can be eliminated by setting the molding region to have a size slightly larger than that of the semiconductor chip 1. Where the lead frame 4 is fabricated to have a size slightly larger than that of the semiconductor chip 1, and the mold is constructed to have a size corresponding to a region defined by the resin dam bars 17 defining the slightly increased size of the lead frame 4, the mold does not come into contact with the end surfaces 1c of the semiconductor chip 1 even when the semiconductor chip 1 has a deviation in size. Accordingly, it is possible to prevent the semiconductor chip 1 from being damaged. Although there is a gap G defined between each end surface 4d of the lead frame 4 and the associated end surface 1c of the semiconductor chip 1, this gap G is filled with the molding resin 11 during the formation of the resin encapsulate 8. Thus, the end surfaces 1c of the semiconductor chip 1 are protected by the mold resin 11 after the formation of the resin encapsulate 8.

Furthermore, in the semiconductor package structure shown in Figs. 1 and 3, if the lead frame is in a state insufficiently fixed in a thickness direction at its portion near the outer leads 4b by the double-sided adhesive tape 3 arranged at the inner lead region during the encapsulating process, the molding resin may spread in the form of a thin film on the surface 4c of the outer leads 4b. In this case, it is necessary to shave off the resin film coated on the surface 4c. The phenomenon of the molding resin spreading on the outer lead surface 4c can be effectively prevented by interposing a double-sided adhesive tape 13 having the same thickness as the double-sided adhesive tape 3 between the semiconductor chip and the outer leads 4b in the vicinity of the periphery of the package. A combination of the structures shown in Figs. 3 and 4 may also be used.

Although the silver plating film 7 is formed over the entire portion of the surface 4c of each outer lead 4b in the structure of Fig. 1, 3 or 4, this may inevitably result in an increase in costs because of an increase in the amount of silver used. However, the amount of silver used can be reduced by reducing the area coated with the silver plating film, as indicated by the reference numeral 14 in Fig. 5. In this case, there is an advantage in regard to costs. The reference numeral 15 denotes an area plated

with no silver plating film.

Fig. 6 illustrates an example in which a solder plating film 16 is formed on the surface 4c of each outer lead 4b. As described above, the formation of the solder plating film on the surface of the outer lead 4b inevitably involves an increase in the number of processes damaging the package. Of course, this is not avoided in the present invention.

In the above mentioned embodiment of the present invention, a semiconductor chip was used which has a thickness of 0.3 mm. The lead frame used has a thickness of 0.15 mm. Also, the double-sided adhesive tape has a total thickness of 0.05 mm. The inner leads were subjected to a coining process to have coining portions having a thickness of 0.075 mm. Although the coining process was used as a method for reducing the thickness of the inner leads, a half-etching process may be used. Although the double-sided adhesive tape was used as a means for attaching the semiconductor chip to the lead frame, an adhesive may be simply used.

[EFFECTS OF THE INVENTION]

In accordance with the present invention, a stepped lead structure is provided by a reduction in the thickness of each inner lead. Accordingly, it is unnecessary to give a machining depth exceeding the lead thickness. Such a machining depth is required in the conventional method in

which a stepped lead structure is provided in accordance with a down-setting process. Thus, it is possible to produce a semiconductor package having a reduced thickness. Since the lead frame has a size slightly larger than that of the semiconductor chip in accordance with the present invention, it is possible to effectively prevent the semiconductor chip from being damaged by the mold.

Moreover, it is possible to prevent the molding resin from spreading on the surfaces of the outer leads because the adhesive adapted to bond the lead frame to the surface of the semiconductor chip is also applied to the outer leads. Accordingly, it is unnecessary to shave off the outer lead surfaces.

HITD U11

emi conductor device with lead frame for high density mounting - has outer lead exposed sealing resin surface

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The device includes a semi conductor chip (1) bonded with a lead frame (4). The lead frame consists of an inner lead (4a) and an outer lead (4b).

A bonding wire (9) is used to bond the inner lead frame and the semi conductor chip. A mould resin (8) is sealed on the surface of the semi conductor chip. The main body has outer lead exposed in a sealing resin surface (8a).

ADVANTAGE - Decreases package thickness. Prevents semi conductor chip from damage. (5pp Dwg.No.2/7)

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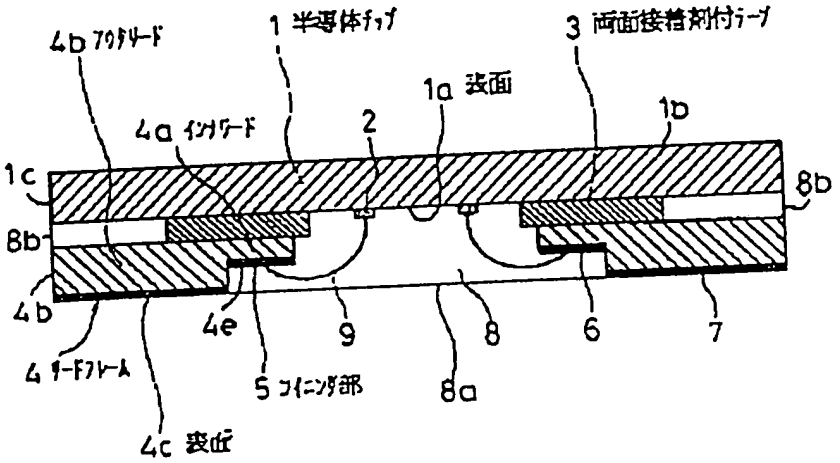

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Japanese Patent Laid-Open Publication No. Heisei 9-8205

[TITLE OF THE INVENTION]

RESIN-ENCAPSULATED SEMICONDUCTOR DEVICE

[CLAIMS]

1. A resin-encapsulated semiconductor device using a lead frame which is shaped in accordance with a two-step etching process to a body wherein a thickness of inner leads is less than that of the lead frame blank, comprising:

inner leads having the thickness less than that of the lead frame blank; and

terminal columns integrally connected to the inner leads and having the same thickness with the lead frame blank, the terminal columns possessing a column-shaped configuration which is adapted to be electrically connected to an external circuit, the terminal columns being disposed outside of the inner leads in a manner such that they are coupled to the inner leads in a direction orthogonal to the thickness-wise direction thereof, the terminal columns having terminal portions arranged on top ends thereof, the terminal portions being made of solders, etc. and exposed to the outside beyond a resin encapsulate, each inner lead possessing a rectangular cross-section and having four

surfaces including a first surface, a second surface, a third surface and a fourth surface, the first surface being flushed with one surface of a remaining portion of the inner lead having the same thickness with the lead frame blank while being opposed to the second surface, and each of the third and fourth surfaces having a concave shape depressed toward the inside of the inner lead.

2. A resin-encapsulated semiconductor device using a lead frame which is shaped in accordance with a two-step etching process to a body wherein a thickness of inner leads is less than that of the lead frame blank, comprising:

inner leads having the thickness less than that of the lead frame blank; and

terminal columns integrally connected to the inner leads and having the same thickness with the lead frame blank, the terminal columns possessing a column-shaped configuration which is adapted to be electrically connected to an external circuit, the terminal columns being disposed outside of the inner leads in a manner such that they are coupled to the inner leads in a direction orthogonal to the thickness-wise direction thereof, portions of top ends of the terminal columns being exposed to the outside beyond a resin encapsulate, each inner lead possessing a rectangular

cross-section and having four surfaces including a first surface, a second surface, a third surface and a fourth surface, the first surface being flushed with one surface of a remaining portion of the inner lead having the same thickness with the lead frame blank while being opposed to the second surface, and each of the third and fourth surfaces having a concave shape depressed toward the inside of the inner lead.

3. The resin-encapsulated semiconductor device as claimed in claims 1 or 2, wherein a semiconductor chip is received inward of the inner leads, and electrodes of the semiconductor chip are electrically connected to the inner leads through wires, respectively.

4. The resin-encapsulated semiconductor device as claimed in claim 3, wherein the lead frame has a die pad, and the semiconductor chip is mounted onto the die pad.

5. The resin-encapsulated semiconductor device as claimed in claim 3, wherein the lead frame does not have a die pad, and the semiconductor chip is fastened to the inner leads using a reinforcing fastener tape.

6. The resin-encapsulated semiconductor device as

claimed in claims 1 or 2, wherein the semiconductor chip is fastened by means of insulating adhesive to the second surfaces of the inner leads on one surface thereof on which the electrodes are located, and the electrodes of the semiconductor chip are electrically connected to the first surfaces of the inner leads through wires, respectively.

7. The resin-encapsulated semiconductor device as claimed in claims 1 or 2, wherein the semiconductor chip is fastened to the second surfaces of the inner leads by bumps thereby to be electrically connected to the inner leads.

[DETAILED DESCRIPTION OF THE INVENTION]

[FIELD OF THE INVENTION]

The present invention relates to a resin-encapsulated semiconductor device capable of meeting the requirement for an increase in the number of terminals and resolving problems which are caused in association with position shift and coplanarity of an outer lead.

[DESCRIPTION OF THE PRIOR ART]

FIG. 15(a) shows the configuration of a generally known resin-encapsulated semiconductor device (a plastic lead frame package). The shown resin-encapsulated semiconductor device includes a die pad 1511 having a

semiconductor chip 1520 mounted thereon, outer leads 1513 to be electrically connected to the associated circuits, inner leads 1512 formed integrally with the outer leads 1513, bonding wires 1530 for electrically connecting the tips of the inner leads 1512 to the bonding pad 1521 of the semiconductor chip 1520, and a resin 1540 encapsulating the semiconductor chip 1520 to protect the semiconductor chip 1520 from external stresses and contaminants. This resin-encapsulated semiconductor device, after mounting the semiconductor chip 1520 on the bonding pad 1521, is manufactured by encapsulating the semiconductor chip 1520 with the resin. In this resin-encapsulated semiconductor device, the number of the inner leads 1512 is equal to that of the bonding pads 1521 of the semiconductor chip 1520. And, FIG. 15(b) shows the configuration of a monolayer lead frame used as an assembly member of the resin-encapsulated semiconductor device shown in FIG. 15a. Such a lead frame includes the bonding pad 1511 for mounting the semiconductor chip, the inner leads 1512 to be electrically connected to the semiconductor chip, the outer lead 1513 which is integral with the inner leads 1512 and is to be electrically connected to the associated circuits. This also includes dam bars 1514 serving as a dam when encapsulating the semiconductor chip with the resin, and a frame 1515 serving to support the entire lead frame 1510.

Such a lead frame is formed from a highly conductive metal such as a cobalt, 42 alloy(a 42% Ni-Fe alloy), copper-based alloy by a pressing working process or an etching process. FIG. 15(b)(D) is a cross-sectional view taken along the line F1-F2 of FIG. 15(b)(イ).

Recently, there has been growing demand for the miniaturization and reduction in thickness of resin-encapsulated semiconductor device employing lead frames like the lead frame (plastic lead frame package) and the increase of the number of terminals of resin-encapsulated semiconductor package as electronic apparatuses are miniaturized progressively and the degree of the integration of semiconductor device increase progressively. Thus, recent resin-encapsulated semiconductor package, particularly quad plate package(QFPs) and thin quad flat packages (TQFPs) have each a greatly increased number of pins.

Lead frames having inner leads arranged at small pitches among lead frames for semiconductor packages are fabricated by a photolithographic etching process, while lead frames having inner leads arranged at comparatively large pitches among lead frames for semiconductor packages are fabricated by press working. However, lead frames having a large number of fine inner leads to be used for forming semiconductor packages having a large number of

pins are fabricated by subjecting a blank of a thickness on the order of 0.25 mm to an etching process, not a press working.

The etching process for forming a lead frame having fine inner leads will be described hereinafter with reference to FIG. 14. First, a copper alloy or 42 alloy thin sheet of a thickness on the order of 0.25 mm (a lead frame blank 1410) is cleaned perfectly (FIG. 14(a)). Then, a photoresist, such as a water-soluble casein photoresist containing potassium dichromate as a sensitive agent, is spread in photoresist films 1420 over the major surfaces of the thin film as shown in FIG. 14(b).

Then, the photoresist films are exposed, through a mask of a predetermined pattern, to light emitted by a high-pressure mercury lamp, and the thin sheet is immersed in a developer for development to form a patterned photoresist film 1430 as shown in FIG. 14(c). Then, the thin sheet is subjected, when need be, to a hardening process, a washing process and such, and then an etchant containing ferric chloride as a principal component is sprayed against the thin sheet 1010 to etch through portions of the thin sheet 1410 not coated with the patterned photoresist films 1020 so that inner leads of predetermined sizes and shapes are formed as shown in FIG. 14(d).

Then, the patterned resist films are removed, the patterned thin sheet 1410 is washed to complete a lead frame having the inner leads of desired shapes as shown in FIG. 14(e). Predetermined areas of the lead frame thus formed by the etching process are silver-plated. After being washed and dried, an adhesive polyimide tape is stuck to the inner leads for fixation, predetermined tab bars are bent, when need be, and the die pad depressed. In the etching process, the etchant etches the thin sheet in both the direction of the thickness and directions perpendicular to the thickness, which limits the miniaturization of inner lead pitches of lead frames. Since the thin sheet is etched from both the major surfaces as shown in FIG. 14 during the etching process, it is said, when the lead frame has a line-and-space shape, that the smallest possible intervals between the lines are in the range of 50 to 100% of the thickness of the thin sheet. From the viewpoint of forming the outer lead having a sufficient strength, generally, the thickness of the thin sheet must be about 0.125 mm or above. Furthermore, the width of the inner leads must be in the range of 70 to 80 □m for successful wire bonding. When the etching process as illustrated in FIG. 14 is employed in fabricating a lead frame, a thin sheet of a small thickness in the range of 0.125 to 0.15 mm is used and inner leads are formed by etching so that the

fine tips thereof are arranged at a pitch of about 1. mm.

However, recent miniature resin-encapsula semiconductor package requires inner leads arranged pitches in the range of 0.13 to 0.15 mm, far smaller t 0.165 mm. When a lead frame is fabricated by processing thin sheet of a reduced thickness, the strength of t outer leads of such a lead frame is not large enough withstand external forces that may be applied thereto the subsequent processes including an assembling proce and a chip mounting process. Accordingly, there is a lim to the reduction of the thickness of the thin sheet t enable the fabrication of a minute lead frame having fir leads arranged at very small pitches by etching.

An etching method previously proposed to overcom such difficulties subjects a thin sheet to an etchin process to form a lead frame after reducing the thickness of portions of the thin sheet corresponding to the inner leads of the lead frame by half etching or pressing to form the fine inner leads by etching without reducing the strength of the outer leads. However, problems arise in accuracy in the subsequent processes when the lead frame is formed by etching after reducing the thickness of the portions corresponding to the inner leads by pressing; for example, the smoothness of the surface of the plated areas

is unsatisfactory, the inner leads cannot be formed in a flatness and a dimensional accuracy required to clamp the lead frame accurately for bonding and molding, and a platemaking process must be repeated twice making the lead fabricating process intricate. It is also necessary to repeat a platemaking process twice when the thickness of the portions of the thin sheet corresponding to the inner leads is reduced by half etching before subjecting the thin sheet to an etching process for forming the lead frame, which also makes the lead frame fabricating process intricate. Thus, this previously proposed etching method has not yet been applied to practical lead frame fabricating processes.

[SUBJECT MATTERS TO BE SOLVED BY THE INVENTION]

On the other hand, because a pitch among inner leads is made narrow as the number of terminals is increased, it is considered important to know whether a problem is caused or not in association with position shift or coplanarity of an outer lead when implementing a chip mounting process. Accordingly, the present invention has been made in an effort to solve the problems occurring in the related art, and an object of the present invention is to provide a resin-encapsulated semiconductor device capable of meeting the requirement for an increase in the number of terminals

and resolving problems which are caused in assoc
position shift and coplanarity of an outer lead.

[MEANS FOR SOLVING THE SUBJECT MATTERS]

According to one aspect of the present
there is provided a resin-encapsulated semiconduc
using a lead frame which is shaped in accordan
two-step etching process to a body wherein a thi
inner leads is less than that of the lead fra
comprising: inner leads having the thickness less
of the lead frame blank; and terminal columns i
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of the inner lead.

According to another aspect of the present inventio
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columns being disposed outside of the inner leads in a
manner such that they are coupled to the inner leads in a
direction orthogonal to the thickness-wise direction
thereof, portions of top ends of the terminal columns being
exposed to the outside beyond a resin encapsulate, outer
surfaces of the terminal columns also being exposed to the
outside beyond the resin encapsulate, each inner lead

possessing a rectangular cross-section and having four surfaces including a first surface, a second surface, a third surface and a fourth surface, the first surface being flushed with one surface of a remaining portion of the inner lead having the same thickness with the lead frame blank while being opposed to the second surface, and each of the third and fourth surfaces having a concave shape depressed toward the inside of the inner lead.

According to another aspect of the present invention, a semiconductor chip is received inward of the inner leads, and electrodes (pads) of the semiconductor chip are electrically connected to the inner leads through wires, respectively. According to another aspect of the present invention, the lead frame has a die pad, and the semiconductor chip is mounted onto the die pad. According to another aspect of the present invention, the lead frame does not have a die pad, and the semiconductor chip is fastened to the inner leads using a reinforcing fastener tape. According to still another aspect of the present invention, the semiconductor chip is fastened by means of insulating adhesive to the second surfaces of the inner leads on one surface thereof on which the electrodes are located, and the electrodes of the semiconductor chip are electrically connected to the first surfaces of the inner leads through wires, respectively. According to yet still

another aspect of the present invention, the semiconductor chip is fastened to the second surfaces of the inner leads by bumps thereby to be electrically connected to the inner leads. In the above descriptions, in the case that the terminal columns have terminal portions which are arranged on top ends of the terminal columns, with the terminal portions made of solders, etc. and exposed to the outside beyond the resin encapsulate, while it is the norm that the terminal portions comprising the solders, etc. are exposed to the outside beyond the resin encapsulate, it is not necessarily required for the terminal portions to be projected beyond the resin encapsulate. Moreover, while it is possible to use the outside surfaces of the terminal columns while they are not encapsulated by the resin encapsulate and they are exposed to the outside, the outside surfaces of the terminal columns which are not encapsulated by the resin encapsulate, can be covered by a protective frame using adhesive, etc.

[WORKING FUNCTIONS]

The resin-encapsulated semiconductor device in accordance with the present invention can meet a demand for an increase in the number of terminals. At the same time, in the resin-encapsulated semiconductor device, because the forming process of the outer leads as in the case of using

a mono-layered lead frame shown in FIG. 13(b) is not required, it is possible to provide a semiconductor device in which no problems are caused in association with position shift and colplanarity of the outer leads. More particularly, the use of a multi-pinned lead frame shaped in a manner that inner leads have a thickness less than that of the lead frame blank by a two-step etching process, that is, the inner leads are arranged at a fine pitch, can meet a demand for an increase in the pin number of the semiconductor device. Furthermore, by using the lead frame which is fabricated by a two-step etching process as will be described later with reference to FIG. 1, the second surface of each inner lead has coplanarity, and is excellent in wire-bonding property. In addition, since the first surface of the inner lead is also a flat surface and the third and fourth surfaces are depressed toward the inside of the inner lead, the inner leads are stable and coplanarity width upon wire bonding process can be enlarged.

[EMBODIMENTS]

Embodiments of the resin-encapsulated semiconductor device in accordance with the present invention will now be described with reference to the attached drawings. First, a resin-encapsulated semiconductor device in accordance

with a first embodiment of the present invention described hereinafter with reference to FIGs. 1 FIG. 1(a) is a cross-sectional view of the encapsulated semiconductor device according to the embodiment of the present invention., FIG. 1(b) is a sectional view of an inner lead taken along the line of FIG. 1(a), and FIG. 1(c) is a cross-sectional vie terminal column taken along the line B1-B2 of FIG. Moreover, FIG. 2(a) is a perspective view of the encapsulated semiconductor device according to the embodiment of the present invention, FIG. 2(b) is a view of the resin-encapsulated semiconductor device o 2(a), and FIG. 2(c) is a bottom view of the encapsulated semiconductor device of FIG. 2(a). In F and 2, a drawing reference numeral 100 represents a encapsulated semiconductor device, 110 a semicond chip, 111 electrodes (pads), 120 wires, 130 a lead f 131 inner leads, 131Aa a first surface, 131Ab a s surface, 131Ac a third surface, 131Ad a fourth surface terminal columns, 133A terminal portions, 133B surfaces, 133S a top surface, 135 a die pad, and 1 resin encapsulate.

In the resin-encapsulated semiconductor d according to the first embodiment, as shown in FIG. the semiconductor chip 110 is placed inward of the

leads 131. As can be readily seen from FIG. 1(a), the semiconductor chip 110 is mounted on the die pad 132 at the surface thereof which is opposed to the other surface thereof where the electrodes (pads) 111 of the semiconductor chip 110 are arranged. Each electrode pad 111 is electrically connected to the second surface 131Ab of the inner lead 131 through the wire 120. The electrical connection between the resin-encapsulated semiconductor device 100 of this embodiment and an external circuit is achieved by mounting the resin-encapsulated semiconductor device 100 via the terminal portions 133A each being made of a semi-spherical solder, on a printed circuit substrate, with the terminal portions 133A located on the top surfaces 133S of the terminal columns 133, respectively. In the resin-encapsulated semiconductor device of the first embodiment of the present invention, it is not necessarily required to provide a protective frame 180, and instead, a structure, as shown in FIG. 1(d), in which no protective frame is used can be adopted.

The lead frame 130 used in the semiconductor device 100 according to the first embodiment is made of a 42% nickel-iron alloy. Therefore, the lead frame 130A which has a contour as shown in FIG. 9(a) and is shaped by an etching process, is used as the lead frame 130. The lead frame 130 has inner leads 131 which are shaped to have a

thickness less than that of the terminal columns 133 or other portions. Dam bars 136 serve as a dam when encapsulating the semiconductor chip 110 with a resin. Moreover, although the lead frame 130A which is processed by etching to have the contour as shown in FIG. 5a is used in this embodiment, the lead frame is not limited to such a contour because portions except the inner leads 131 and the terminal columns 133 are not necessary. The inner leads 131 have a thickness of 40 □m whereas the portions of the lead frame 130 other than the inner leads 131 have a thickness of 0.15 mm which corresponds to the thickness of the lead frame blank. The other portions of the lead frame 130 except the inner leads 131 may not have the thickness of 0.15 mm, but have a thickness of 0.125 mm-0.50 mm which is thinner. The tips of the inner leads 131 have a small pitch of 0.12 mm so as to achieve an increase in the number of terminals for semiconductor devices. The second face 131Ab of the inner lead 131 has a substantially flat profile so as to allow an easy wire boding thereon. Also, as shown in FIG. 1(b), because the third and fourth faces 131Ac and 131Ad have a concave shape which is depressed toward the inside of the associated inner lead, a high strength can be obtained even though the second face (wire bonding surface) 131Ab is narrowed.

In the present embodiment, since twisting does not

occur in the inner leads 131 irrespective of whether the inner leads 131 is long or not. The inner leads having the contour, as shown in FIG. 9(a), in which the tips of the inner leads 131 are separated one from another, are prepared by the etching process, and the inner leads are resin-encapsulated after mounting the semiconductor chip thereon as will be described later. However, where the inner leads 131 are long in their length and have a tendency for the generation of twisting therein, it is impossible to fabricate the lead frame by etching to have the contour as shown in FIG. 9(a). Therefore, after etching the lead frame in a state where the tips of the inner leads are fixed to the connecting portion 131B as shown in FIG. 9(c)(イ), the inner leads 131 are fixed with the reinforcing tape 160 as shown in FIG. 9(c)(ロ). Then, the connecting portions 131B which are not necessary in the fabrication of the resin-encapsulated semiconductor device are removed by a press as shown in FIG. 9(c)(ハ), and a semiconductor device is then mounted on the lead frame.

Hereinafter, a method for the fabrication of the resin-encapsulated semiconductor device will now be described with reference to FIG. 8. First, the lead frame 130A, as shown in FIG. 9(a), which is shaped by the etching process as will be described later, is prepared such that the second surfaces 131Ab of the inner leads 131 are

directed upward (FIG. 8(a)).

Then, the semiconductor chip 110 is mounted onto the die pad 135 such that the surfaces of the semiconductor chip 110 on which the electrodes 111 are arranged, are directed upward (FIG. 8(b)).

Next, after the semiconductor chip 110 is fastened onto the die pad 135, the electrodes 111 of the semiconductor chip 110 and the second surfaces 131Bb of the inner leads 131 are bonded with each other using wires 120 (FIG. 8(c)).

Subsequently, encapsulation is carried out with the conventional resin encapsulate 140. Thereafter, unnecessary portions of the lead frame 130 which are protruded from the resin encapsulate 140 are cut by a press to form terminal columns 133 and also the side surfaces 133B of the terminal columns 133 (FIG. 8(d)).

Then, the dam bars 136, the frame portions 137, etc. of the lead frame 130A as shown in FIG. 9 are removed. Next, the terminal portions 133A each made of the semi-spherical solder are arranged on the outer surface of each terminal column 133 to fabricate a resin-encapsulated semiconductor device (FIG. 8(e)).

Thereafter, the protective frame 180 is arranged by means of adhesive around an entire outer surface of the resultant structure in such a manner that the side surfaces

of the terminal columns 133 are covered thereby FIG. 8(f)). At this time, the protective frame 180 functions to reinforce the semiconductor device. In other words, the protective frame 180 serves to prevent moisture from leaking into a gap between the resin encapsulate and the terminal columns due to the fact that the side surfaces of the terminal columns are exposed to the outside, whereby a crack is not formed in the semiconductor device and the breakage of the semiconductor device is avoided. However, persons skilled in the art will readily appreciate that it is not necessarily required to provide the protective frame 180. Also, when such an encapsulating process by the resin is carried out using a desired mold, the encapsulating process is implemented in a state wherein the outer side surfaces of the terminal columns of the lead frame are somewhat protruded out of the resin encapsulate.

A method for etching the lead frame of the first embodiment will now be described in conjunction with the attached drawings. FIG. 11 is of cross-sectional views respectively illustrating sequential steps of the etching process for the lead frame of the first embodiment. In particular, the cross-sectional views of FIG. 1 correspond to a cross section taken along the line D1-D2 of FIG. 9(a). In FIG. 11, the reference numeral 1110 denotes a lead frame blank, 1120A and 1120B resist patterns, 1130 first opening,

1140 second openings, 1150 first concave portions, 1161 second concave portions, 1170 flat surfaces, and 1180 an etch-resistant layer. First, a water-soluble casein resist using potassium dichromate as a sensitive agent is coated over both surfaces of the lead frame blank 1110 made of a 42% nickel-iron alloy and having a thickness of about 0.15 mm. Using desired pattern plates, the resist films are patterned to form resist patterns 1120A and 1120B having first opening 1130 and second openings 1140, respectively (FIG. 11(a)).

The first opening 1130 is adapted to etch the lead frame blank 1110 to have a flat etched bottom surface to a thickness smaller than that of the lead frame blank 1110 in a subsequent process. The second openings 1140 are adapted to form desired shapes of tips of inner leads. Although the first opening 1130 includes at least an area forming the tips of the inner leads 1110, a topology generated by partially thinned portion by etching in a subsequent process can cause hindrance in a taping process or a clamping process for fixing the lead frame. Thus, an area to be etched needs to be large without being limited to fine portions of the tips of the inner leads. Thereafter, both surfaces of the lead frame blank 1110 formed with the resist patterns are etched using a 48 Be' ferric chloride solution of a temperature of 57℃ at a spray pressure of

2.5 kg/cm^2. The etching process is terminated at the point of time when first recesses 1150 etched to have a flat etched bottom surface have a depth h corresponding to 1/3 of the thickness of the lead frame blank (FIG. 11 c).

Although both surfaces of the lead frame blank 1110 are simultaneously etched in the primary etching process, it is not necessary to simultaneously etch both surfaces of the lead frame blank 1110. The reason why both surfaces of the lead frame blank 1110 are simultaneously etched, as in this embodiment, is to reduce the etching time taken in a secondary etching process as will be described later. The total time taken for the primary and secondary etching processes is less than that taken in the case of etching of only one surface of the lead frame blank on which the resist pattern 1120B is formed. Subsequently, the surface provided with the first recesses 1150 respectively etched at the first opening 1130 is entirely coated with an etch-resistant hot-melt wax (acidic wax type MR-WB6, The Inctec Inc.) by a die coater to form an etch-resistant layer 1180 so as to fill up the first recesses 1150 and to cover the resist pattern 1120A (FIG. 11(c)).

It is not necessary to coat the etch-resistant layer 1180 over the entire portion of the surface provided with the resist pattern 1120A. However, it is preferred that the etch-resistant layer 1180 be coated over the entire

portion of the surface formed with the first recesse
and first opening 1130, as shown in FIG. 11(c), beca
is difficult to coat the etch-resistant layer 1180 o
the surface portion including the first recesses
Although the etch-resistant layer 1180 wax employed i
embodiment is an alkali-soluble wax, any suitabl
resistant to the etching action of the etchant soluti
remaining somewhat soft during etching may be used.
for forming the etch-resistant layer 1180 is not limit
the above-mentioned wax, but may be a wax of a UV-se
type. Since each first recess 1130 etched by the pr
etching process at the surface formed with the pa
adapted to form a desired shape of the inner lead t
filled up with the etch-resistant layer 1180, it is
further etched in the following secondary etching proc
The etch-resistant layer 1180 also enhances the mechan
strength of the lead frame blank for the second etc
process, thereby enabling the second etching process t
conducted while keeping a high accuracy. It is
possible to enable a second etchant solution to be spr
at an increased spraying pressure, for example, 2.5 kg
or above, in the secondary etching process. The increa
spraying pressure promotes the progress of etching in
direction of the thickness of the lead frame blank in
secondary etching process. Then, the lead frame blank

subjected to a secondary etching process. In this secondary etching process, the lead frame blank 1110 is etched at its surface formed with first recesses 1150 having a flat etched bottom surface, to completely perforate the second recesses 1160, thereby forming the tips of inner leads 131A (FIG. 11(d)).

The bottom surface 1170 of each recess formed by the primary etching process is flat. However, both side surfaces of each recess positioned at opposite sides of the bottom surface 1170 have a concave shape depressed toward the inside of the inner lead. Then, the lead frame blank is cleaned. After completion of the cleaning process, the etch-resistant layer 1180, and resist films (resist patterns 1120A and 1120B) are sequentially removed. Thus, a lead frame 130A having a structure of FIG. 9(a) is obtained in which tips of the inner leads 131A are arranged at a fine pitch. The removal of the etch-resistant layer 1180 and resist films (resist patterns 1120A and 1120B) is achieved using a sodium hydroxide solution serving to dissolve them.

The processes for manufacturing the lead frame as shown in FIG. 11, is to form by means of etching the lead frame having the tips of the inner leads used in this embodiment of the present invention, which have a thickness less than that of the lead frame. Especially, the first

surfaces 131Aa of the tips of the inner leads as shown in FIG. 1, are flushed with one surfaces of remaining portions of the inner leads having the same thickness with the lead frame while being opposed to the second surfaces 131Ab, and the third and fourth surfaces are formed to have a concave shape which is depressed toward the inside of the inner leads. Where a semiconductor chip is mounted on the second surfaces 131Ab of the inner leads by means of bumps for an electrical connection therebetween, as in a semiconductor device according to a third embodiment as will be described hereinafter, an increased tolerance for the connection by bumps is obtained when the second surface 131Ab has a concave shape depressed toward the inside of the inner lead. To this end, an etching method shown in FIG. 12 is adopted in this case. The etching method shown in FIG. 12 is the same as that of FIG. 11 in association with its primary etching process. After completion of the primary etching process, the etching method is conducted in a manner different from that of the etching method of FIG. 11 in that the second etching process is conduced at the side of the first recesses 1150 after filling up the second recesses 1160 by the etch-resist layer 1180, thereby completely perforating the second recesses 1160. At this time, by implementing the primary etching process, etching at the side of the second openings 1140 is performed in a

sufficient manner. The cross section of each inner lead, including its tip, formed in accordance with the etching method of FIG. 12, has a concave shape depressed toward the inside of the inner lead at the second surface 131Ab, as shown in FIG. 6(b).

The etching method in which the etching process is conducted at two separate steps, respectively, as in that of FIGs. 11 and 12, is generally called a "two-step etching method". This etching method is advantageous in that a desired fineness can be obtained. The etching method used to fabricate the lead frame 130A of the first embodiment shown in FIG. 9 involves the two-step etching method and the method for forming a desired shape of each lead frame portion while reducing the thickness of each pattern formed. In particular, the etching method makes it possible to achieve a desired fineness. In accordance with the method illustrated in FIGs. 11 and 12, the fineness of the tip of each inner lead 131A formed by this method is dependent on the shape of the second recesses 116O and the thickness t of the inner lead tip which is finally obtained. For example, where the blank has a thickness t reduced to 50 □m, the inner leads can have a fineness corresponding to a lead width W1 of 100 □m and a tip pitch p of 0.15 mm, as shown in FIG. 11(e). In the case of using a small blank thickness t of about 30 □m and a lead

width W1 of 70 □m, it is possible to form inner leads having a fineness corresponding to an inner lead pitch p of 0.12 mm. Of course, it may be possible to form inner leads having a further reduced tip pitch by adjusting the blank thickness t and the lead width W1. That is to say, an inner lead tip pitch p up to 0.08 mm, a blank thickness up to 25 □m , and a lead width W1 up to 40 □m can be obtained.

In the case where twisting of the inner leads does not occur in the fabricating process, as in the case where the inner leads are short in their length, a lead frame illustrated in FIG. 9(a) can be directly obtained. However, where the inner leads are long in length as compared to those of the first embodiment, the inner leads have tendency for the generation of twisting. Thus, in this case, the lead frame is obtained by etching in a state where the tips of the inner leads are bound to each other by a connecting member 131B as shown in FIG. 9(c)(イ). Then, the connecting member 131B which is not necessary for the fabrication of a semiconductor package is cut off by means of a press to obtain a lead frame shaped as shown in FIG. 9(a).

Moreover, as described above, where unnecessary portions in a structure shown in FIG. 9(c)(イ) are cut to obtain the lead frame having the contour shown in FIG.

9(a), a reinforcing tape 160 (a polyimide tape is generally used, as shown in FIG. 9(c)(A). While the connecting member 131B is cut off by means of a press to obtain the contour shown in FIG. 9(c)(B), a semiconductor device is mounted on the lead frame still having the reinforcing tape attached thereon. Also, the mounted semiconductor device is encapsulated with a resin in a condition where the lead frame still has the tape. The line E11-E12 illustrates a cut portion.

The tip of the inner lead 131 of the lead frame used in the semiconductor device of this first embodiment has a cross-sectional shape as shown in FIG. 13(A)(a). The tip 131A has an etched flat surface (second surface) 131Ab which is substantially flat and therefore has a width W1 slightly greater than the width W2 of an opposite surface. The widths W1 and W2 (about 1000 μm) are more than the width W at the central portion of the tips when viewed in the direction of the inner lead thickness. Thus, the tip of the inner lead has a cross-sectional shape having opposite wide surfaces. To this end, although either of the opposite surfaces of the tip 131A can be easily electrically connected to a semiconductor device (not shown) by a wire 120A or 120B, this embodiment illustrates the use of the etched flat surface for wire-bonding as shown in FIG. 13(B)(a). In FIG. 13, a reference numeral

1331Ab depicts an etched flat surface, 1331Aa a surface of a lead frame blank, and 121A and 121B, respectively, a plated portion. In the case of FIG. 13(B)(a), there has particularly excellent in wire-bonding property, because the etched flat surface does not have roughness. FIG. 13(A) shows that the tip 1331B of the inner lead of the lead frame fabricated according to the process illustrated in FIG. 14 is wire-bonded to a semiconductor device. In this case, however, both the opposite surfaces of the tip 1331B of the inner lead are flat, but have a width smaller than that in a direction of the inner lead thickness. In addition to this, as both the opposite surfaces of the tip 1331B is formed of surfaces of the lead frame blank, these surfaces have an inferior wire-bonding property as compared to that of the etched flat surface of this first embodiment. FIG. 13(C) shows that the inner lead tip 1331C or 1331D, obtained by thinning in its thickness by a means of a press (coining) and then by etching, is wire-bonded to a semiconductor device (not shown). In this case, however, a pressed surface of the inner lead tip is not flat as shown FIG. 13(C). Thus, the wire-bonding on either of the opposite surfaces as shown in FIG. 13(C)(a) or FIG. 13(C)(b) often results in an insufficient wire-bonding stability and a problematic quality. The drawing reference numeral 1331Ab represents a coining surface.

A modified example of the resin-encapsulated semiconductor device in accordance with the first embodiment of the present invention will described hereinafter. FIGs. 3(a) through 3(e) are cross-sectional views of the modified example of the resin-encapsulated semiconductor device in accordance with the first embodiment of the present invention. The semiconductor device of the modified example as shown in FIG. 3(a), is different from that of the first embodiment in that a position of the die pad 135 is changed, that is, the die pad 135 is exposed to the outside. By the fact that the die pad 135 is exposed to the outside, the heat dissipation property is improved as compared to the first embodiment. Also, in the semiconductor device of the modified example as shown in FIG. 3(b), because the die pad 135 is exposed to the outside, the heat dissipation property is improved as compared to the first embodiment. Unlike the first embodiment or the modified example as shown in FIG. 3(a), in the present modified example as shown in FIG. 3(b), because a direction of the semiconductor device 110 is changed, the first surfaces of the lead frame are established as the wire bonding surfaces. The modified examples as shown in FIGs. 3(c), 3(d) and 3(e), illustrate semiconductor devices which are obtained by modifying the semiconductor devices of the first embodiment, the modified

example as shown in FIG. 3(a) and the modified example as shown in FIG. 3(b), wherein the semi-spherical solders are not used, and instead, the top surfaces of the terminal columns are directly used as the terminal portions, whereby an entire manufacturing procedure can be simplified.

Next, a resin-encapsulated semiconductor device in accordance with a second embodiment of the present invention will be described. FIG. 4(a) is a cross-sectional view of the resin-encapsulated semiconductor device in accordance with the second embodiment of the present invention, FIG. 4(b) is a cross-sectional view illustrating inner leads, taken along the line A3-A4 of FIG. 4(a), and FIG. 4(c) is a cross-sectional view illustrating a terminal column, taken along the line B3-B4 of FIG. 4(a). Because an outer appearance of the semiconductor device of the second embodiment is substantially the same as that of the first embodiment, it is not illustrated in the drawings. In FIG. 3, the drawing reference numeral 200 represents a semiconductor device, 210 a semiconductor chip, 211 electrodes (pads), 220 wires, 230 a lead frame, 231 inner leads, 231Ab a second surface, 231Ac a third surface, 231Ad a fourth surface, 233 terminal columns, 233A terminal portions, 233B side surfaces, 233S top surfaces, 240 a resin encapsulate, and 270 a reinforcing fastener tape. In the semiconductor device of

this second embodiment, the lead frame 230 does not have a die pad, the semiconductor chip 210 is fastened to the inner leads 231 by the reinforcing fastener tape 240, and the semiconductor chip 210 is electrically connected at its electrodes (pads) 211 to the second surfaces 231Ab of the inner leads 231 by wires 220. Also, in the case of this second embodiment, similarly to the first embodiment, the electrical connection between the resin-encapsulated semiconductor device 200 of this embodiment and an external circuit is achieved by mounting the resin-encapsulated semiconductor device 200 via the terminal portions 233A each being made of a semi-spherical solder, on a printed circuit substrate, with the terminal portions 233A located on the top surfaces 233S of the terminal columns 233, respectively.

In addition, the semiconductor device of this second embodiment does not have a die pad as shown in FIGs. 10(a) and 10(b). The manufacturing method of the semiconductor device of this embodiment using the lead frame 230A which is shaped by the etching process is substantially the same as that of the first embodiment except that, while in the case of the first embodiment, the wire bonding process and resin encapsulating process are performed in a state wherein the semiconductor chip is fastened to the inner leads, in the case of the second embodiment, the wire

bonding process and resin encapsulating process are performed in a state wherein the semiconductor chip 210 is fastened together with the inner leads 231 by the reinforcing fastener tape 270. Also, the cutting process for the unnecessary portions and the terminal portion forming process after resin encapsulating process are implemented in the same way as the first embodiment. The lead frame 230 as shown in FIG. 10(a) is obtained in the same manner by which the lead frame 130A as shown in FIG. 9(a) is obtained. In other words, by cutting the resultant structure obtained after etching the structure as shown in FIG. 10(c)(イ), the contour as shown in FIG. 10(a) is obtained. At this time, the conventional reinforcing fastener tape 260 (the polyimide tape) as shown in FIG. 10(c)(ロ), which performs a reinforcing function is used.

FIG. 5(a) through 5(c) are cross-sectional views illustrating modified examples of the semiconductor device of the second embodiment. The semiconductor device as shown in FIG. 5(a) is different from the semiconductor device of the second embodiment, in that the surface of the semiconductor chip thereof which has the electrodes is directed downward. The modified examples as shown in FIGs. 5(b) and 5(c), illustrate semiconductor devices which are obtained by modifying the semiconductor devices of the second embodiment and the modified example as shown in FIG.

5(a), wherein the semi-spherical solders are not used, and instead, the top surfaces of the terminal columns are directly used as the terminal portions. In these examples, because a protective frame is not used and the side surfaces 333B of the terminal columns 333 are exposed to the outside, a checking operation by a test, etc. can be easily performed.

Hereinafter, a resin-encapsulated semiconductor device in accordance with a third embodiment of the present invention will be described. FIG. 6(a) is a cross-sectional view of the resin-encapsulated semiconductor device of the third embodiment, FIG. 6(b) is a cross-sectional view illustrating inner leads, taken along the line A5-A6 of FIG. 6(a), and FIG. 6(c) is a cross-sectional view illustrating a terminal column, taken along the line B5-B6 of FIG. 6(b). Because an outer appearance of the semiconductor device of the this third embodiment is substantially the same as that of the first embodiment, it is not illustrated in the drawings. In FIG. 6, the drawing reference numeral 300 represents a semiconductor device, 310 a semiconductor chip, 312 bumps, 330 a lead frame, 331 inner leads, 331Aa a first surface, 331Ab a second surface, 331Ac a third surface, 331Ad a fourth surface, 333 terminal columns, 333A terminal portions, 333B side surfaces, 333S top surfaces, 340 a resin encapsulate, and 350 a

reinforcing fastener tape. In the semiconductor device of this third embodiment, the semiconductor chip 310 is fastened to the second surfaces 331Ab of the inner leads 331 by the bumps 311 thereby to be electrically connected to the second surfaces 331Ab. The lead frame 330 has a contour as shown in FIGs. 10(a) and 10(b), which is formed by the etching process of FIG. 11. As shown in FIG. 13(1)(b), both widths W1A and W2A (about 100 □m) at top and bottom ends of the inner leads 331 are larger than a width WA at a center portion in a thickness-wise direction. Due to the fact that the second surfaces 331Ab of the inner leads 331 is depressed toward the inside of the inner leads and the first surfaces 331Aa are flat, a desired fineness can be obtained. Also, when the second surfaces 331Ab of the inner leads 331 are electrically connected to the semiconductor chip via bumps, easy connection can be accomplished as shown in FIG. 13(□)(b). Further, in the case of this third embodiment, as in the case of the first and second embodiments, the electrical connection between the resin-encapsulated semiconductor device 300 of this embodiment and an external circuit is achieved by mounting the resin-encapsulated semiconductor device 300 via the terminal portions 333A each being made of a semi-spherical solder, on a printed circuit substrate, with the terminal portions 333A located on the top surfaces of the terminal

columns 333, respectively.

In addition, unlike the semiconductor device of the first embodiment, the semiconductor device of this third embodiment uses a lead frame which is shaped by the etching process as shown in FIG. 12. However, the manufacturing method of the semiconductor device of this embodiment is substantially the same as that of the first embodiment except that, while in the case of the first embodiment, the wire bonding process and resin encapsulating process are performed in a state wherein the semiconductor chip is fastened to the inner leads, in the case of this third embodiment, the wire bonding process and resin encapsulating process are performed in a state wherein the semiconductor chip 310 is fastened to the inner leads 331 via the bumps. Also, the cutting process for the unnecessary portions and the terminal portion forming process after resin encapsulating process are implemented in the same way as the first embodiment.

FIG. 6(d) is a cross-sectional view illustrating a modified example of the semiconductor device in accordance with the third embodiment of the present invention. In the modified example of the semiconductor device as shown in FIG. 6(d), the terminal portions each comprising the semi-spherical solder are not provided, and the top surfaces of the terminal columns are directly used as the terminal

portions. Because the protective frame is not used and the side surfaces 333B of the terminal columns 333 are exposed to the outside, a checking operation by a test, etc. can be easily performed.

Hereinafter, a resin-encapsulated semiconductor device in accordance with a fourth embodiment of the present invention will be described. FIG. 7(a) is a cross-sectional view of the resin-encapsulated semiconductor device of the fourth embodiment, FIG. 7(b) is a cross-sectional view illustrating inner leads, taken along the line A7-A8 of FIG. 7(a), and FIG. 7(c) is a cross-sectional view illustrating a terminal column, taken along the line B7-B8 of FIG. 7(b). Because an outer appearance of the semiconductor device of the this fourth embodiment is substantially the same as that of the first embodiment, it is not illustrated in the drawings. In FIG. 7, the drawing reference numeral 400 represents a semiconductor device, 410 a semiconductor chip, 411 pads, 430 a-lead frame, 431 inner leads, 431Aa a first surface, 431Ab a second surface, 431Ac a third surface, 431Ad a fourth surface, 433 terminal columns, 433A terminal portions, 433B side surfaces, 433S top surfaces, 440 a resin encapsulate, and 470 insulating adhesive. In the semiconductor device of this fourth embodiment, one surface of the semiconductor chip 410 on which the pads 411 are disposed is fastened to the second

surfaces 431Ab of the inner leads 431 by the insul adhesive 470, and the pads 411 and the first surfaces of the inner leads 431 are electrically connected with other by wires 420. The semiconductor device of fourth embodiment uses the same lead frame which is use the third embodiment, which has the contour as show FIG. 10(a) and 10(b). Also, in the case of this fo embodiment, as in the case of the first and sec embodiments, the electrical connection between the res encapsulated semiconductor device 400 of this embodim and an external circuit is achieved by mounting the res encapsulated semiconductor device 400 via the termi portions 433A each being made of a semi-spherical solde on a printed circuit substrate, with the terminal portio 433A located on the top surfaces of the terminal colum 433, respectively.

FIG. 7(d) is a cross-sectional view illustrating modified example of the semiconductor device in accordanc with the fourth embodiment of the present invention. I the modified example of the semiconductor device as shov in FIG. 7(d), the terminal portions each comprising th semi-spherical solder are not provided, and the to surfaces of the terminal columns are directly used as th terminal portions. Because the protective frame is not used and the side surfaces 433B of the terminal columns 43

are exposed to the outside, a checking operation by a test, etc. can be easily performed.

[EFFECTS OF THE INVENTION]

The present invention provides a resin-encapsulated semiconductor device employing the above-mentioned lead frame, which is capable of meeting a demand for the increased terminal number. Furthermore, the resin-encapsulated semiconductor device in accordance with this invention does not require a process of cutting or bending the dam bars as in the case of using a lead frame having outer leads as shown in FIG. 13(b). As a result of this, the resin-encapsulated semiconductor device does not have a problem in that the outer leads are bent, or a problem associated with coplanarity. In addition to these advantages, the resin-encapsulated semiconductor device has a shortened interconnection length as compared to the QTP or the BGA, whereby the semiconductor device can be reduced in a parasitic capacity, and shortened in a transfer delay time.

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